

# MA2SP02

## Silicon epitaxial planar type

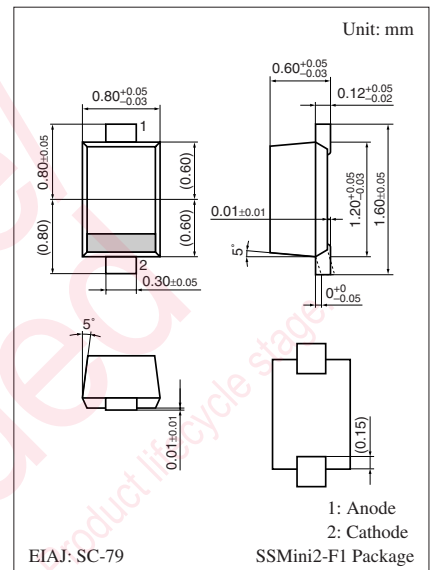
For high frequency switch

### ■ Features

- Small terminal capacitance  $C_t$
- Small forward dynamic resistance  $r_f$
- Miniature package and surface mounting type

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	60	V
Forward current	$I_F$	100	mA
Power dissipation	$P_D$	150	mW
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

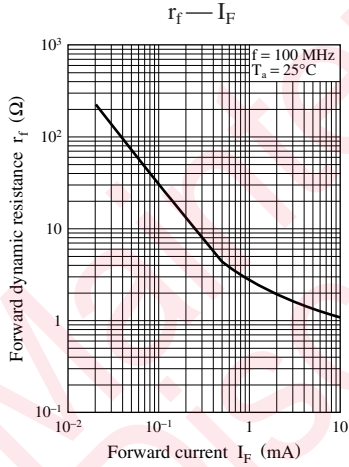
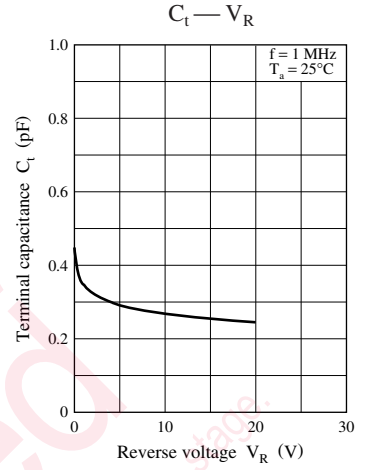
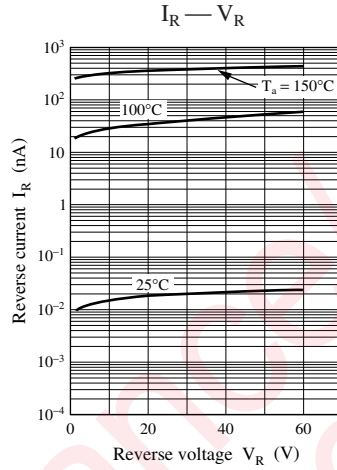
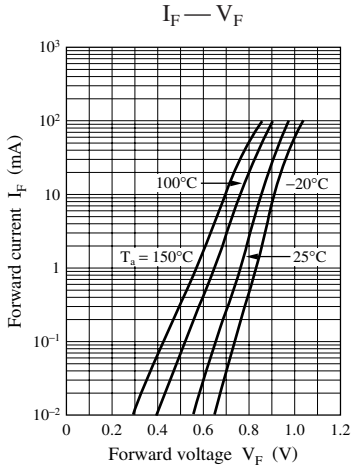


Marking Symbol: 3P

### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_F$	$I_F = 10 \text{ mA}$			1.0	V
Reverse current	$I_R$	$V_R = 60 \text{ V}$			100	nA
Terminal capacitance	$C_t$	$V_R = 1 \text{ V}, f = 1 \text{ MHz}$			0.5	pF
Forward dynamic resistance	$r_f$	$I_F = 10 \text{ mA}, f = 100 \text{ MHz}$			2.0	$\Omega$

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.



Maintenance/Discontinued includes following four Product lifecycle stage:  
 planned maintenance type  
 maintenance type  
 planned discontinued type  
 discontinued type  
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